

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/653976	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 16:39
S2	4	((("6429044") or ("5939772"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 18:12
S3	2	("6473336").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:45
S4	1	10/606733	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 18:20
S5	1	10/653976	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 18:22
S6	1	10/702574	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 18:22
S7	3126	(high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:43
S8	926	(high-permeability high near permeability high?permeability) near magnetic adj material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:49
S9	1944	magnetic near memory near device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:25

S10	10	package with S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:58
S11	1	S9 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:50
S12	138	package and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:13
S13	1	S9 and S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:59
S14	8	S8 and S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:59
S15	11	S7 and S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 09:59
S16	10	S12 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 10:53
S17	8138	(257/433,659,666,678,729).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 12:27
S18	4	((("6429044") or ("5939772")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 12:27
S19	3	S18 and permeab\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 12:27

S20	5875	magnetic near memory near device MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:50
S21	15	S20 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:29
S22	0	S20 and encapsul%4 near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:29
S23	2	S20 and encapsul\$4 near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:32
S24	7	S20 and resin and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:37
S25	8859	encapsul\$4 near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:32
S26	1673	S25 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:34
S27	0	S26 and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:33
S28	0	S26 and (magnetic near memory MRAM)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:33
S29	654770	S26 and die bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:34

S30	92	S26 and die adj bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:35
S31	0	S30 and die adj bond\$3 near3 agent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:35
S32	92	S30 and die adj bond\$3 withagent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:35
S33	0	S30 and die adj bond\$3 with agent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:36
S34	9	S30 and die adj bond\$3 near3 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:57
S35	0	S34 and ((conductive adj lead) near3 (cu copper fe iron))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:41
S36	5	S26 and ((conductive adj lead) near3 (cu copper fe iron))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:49
S37	180	S26 and ((lead adj frame) near3 (cu copper fe iron))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 18:42
S38	0	S20 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:51
S39	5875	(magnetic near memory near device) MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:45

S40	0	S7 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:52
S41	0	S9 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:52
S42	1348099	S37 magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:52
S43	14	S37 and magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 15:56
S44	0	S43 and die adj bond\$3 near3 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:58
S45	10	S43 and die near3bond\$3 near3 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:57
S46	0	S43 and die near3 bond\$3 near3 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:58
S47	0	S43 and die with bond\$3 near3 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:58
S48	4	S43 and die adj bond\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 17:18
S49	11867	encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 17:18

S50	0	S26 and (((lead adj frame) near3 (cu copper fe iron))) with S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 18:42
S51	0	S26 and (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:02
S52	9	resin near3 (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:52
S53	19	resin near5 (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:52
S54	19	resin near5 (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 18:54
S55	1	S54 with lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 18:54
S56	1	S54 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 18:54
S57	31	S39 and (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:04
S58	41	S39 and (stacked multi) near chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:06
S59	15069	(stacked multi) near chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:07

S60	5024	stack\$3 near (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:08
S61	24	S39 and stack\$3 near (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:46
S62	1	S61 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:09
S63	2891	flip adj chip and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:14
S64	169	S63 and magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:10
S65	2476	((chip near2 stack\$3) multichip multi near chip) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:16
S66	1207	S65 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:16
S67	306	S65 and encapsulat\$3 with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:16
S68	271	S65 and encapsulat\$3 near5 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:16
S69	162	S65 and encapsulat\$3 near resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:19

S70	9	S69 and magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:19
S71	180904	(memory near device) MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:46
S72	213635	(memory near device) MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:46
S73	786	S72 and stack\$3 near (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:47
S74	4664	MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:47
S75	21	S74 and stack\$3 near (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 19:47
S76	5875	magnetic near memory near device MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:37
S77	1	S76 and resin and lead adj frame and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:38
S78	8859	encapsul\$4 near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:38
S79	1673	S78 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:38

S80	92	S79 and die adj bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:38
S81	28	S80 and resin and lead adj frame and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:41
S82	3126	(high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:41
S83	10	package with S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:41
S84	2	S83 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:44
S85	138	package and S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:44
S86	6	S85 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:45
S87	28	S80 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:46
S88	5875	(magnetic near memory near device) MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:46
S89	31	S88 and (high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:46

S90	1	S89 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:46
S91	41	S88 and (stacked multi) near chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:46
S92	2	S91 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:47
S93	2891	flip adj chip and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 21:47
S94	169	S93 and magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 21:47
S95	26	S94 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:48
S96	926	(high-permeability high near permeability high?permeability) near magnetic adj material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:48
S97	1944	magnetic near memory near device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:48
S98	8	S96 and S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:48
S99	1	S98 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:48

S10 0	3126	(high-permeability high near permeability high?permeability) near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:09
S10 1	5868	magnetic near memory near device MRAM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:08
S10 2	30	S101 and S100	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:08
S10 3	1	S102 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:10
S10 4	22956	permeab\$6 near magnetic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:09
S10 5	166	S101 and S104	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:10
S10 6	1	S105 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:10
S10 7	18	S101 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:13
S10 8	138	package and S100	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:13
S10 9	6	S108 and heat adj.sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:17

S11 0	10	S108 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:18
S11 1	1	S110 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18
S11 2	8863	encapsul\$4 near3 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:18
S11 3	1676	S112 and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:18
S11 4	92	S113 and die adj bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 09:18
S11 5	28	S114 and heat adj sink	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:19